

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Cheung, et al.

Serial No.: 09/609,347

Confirmation No.: 5540

Filed: July 5, 2000

For: Apparatus for Electro-
Chemical Deposition of
Copper Metalization With
Thermal Annealing

Group Art Unit: 1741

Examiner: E. Smith-Hicks

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

CERTIFICATE OF MAILING 37 CFR 1.8	
I hereby certify that this correspondence is being deposited on _____ with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Washington, D.C. 20231.	
Date _____	Gero G. McClellan

PROPOSED RESPONSE TO OFFICE ACTION DATED JUNE 25, 2002

In response to the Office Action dated June 25, 2002, having a shortened statutory period for response set to expire on September 25, 2002, please consider this response and reconsider the claims pending in the application for reasons discussed below.

IN THE CLAIMS:

Please cancel claims 12-18 without prejudice.

Please amend the following claims:

1. An electro-chemical deposition system, comprising:
a mainframe having a mainframe wafer transfer robot;
a loading station disposed in connection with the mainframe;
one or more electrochemical deposition cells disposed in connection with the mainframe; and
a thermal anneal chamber disposed in connection with the mainframe.